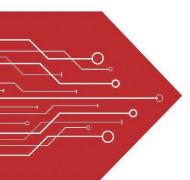
MSKSEMI















ESD

TVS

TSS

MOV

GDT

PLED

Product data sheet

www.msksemi.com

Features

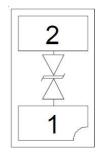
- ♦ 84W (8/20µs) Peak Pulse Power
- ♦ Bidirectional ESD Protection
- ♦ SOD-882 Package
- ♦ RoHS Compliant
- ♦ Matte Tin Lead finish (Pb-Free)
- ♦ Protects One Line
- ♦ Meet IEC61000-4-2 Level 4:

Contact Discharge: 30kV Air Discharge: 30kV

Applications

- \Diamond Communication System
- ♦ Portable Instrumentation
- ♦ Audio and Video Equipment
- ♦ Computers and Peripherals
- ♦ Cellular Handsets and Accessories





DFN1006

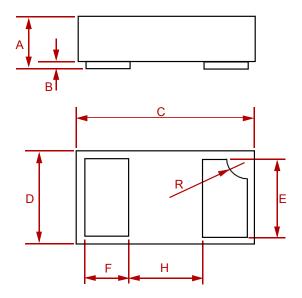
Maximum Ratings (Ta = 25℃)

Symbol	Parameter	Value	Unit
РРК	Peak Pulse Power	84	W
IPP	Peak Pulse Current	6	А
VESD (Contact)	Contact ESD Voltage per IEC61000-4-2	30	kV
VESD (Air)	Air ESD Voltage per IEC61000-4-2	30	kV
TJ	Junction Temperature	-55 to +150	°C
TSTG	Storage Temperature	-55 to +150	°C

Electrical Characteristics (Ta = 25℃)

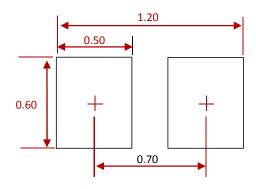
Symbol	Parameter	Conditions	Min	Тур	Max	Unit
VRWM	Reverse Working Peak Voltage				5	V
VBR	Reverse Breakdown Voltage	IT = 1mA	6		9.5	V
IR	Reverse Leakage Current	VRWM = 5V			0.5	μA
VC	Clamping Voltage	IPP = 1A (8/20μs)			9	V
VC	Clamping Voltage	IPP = 6A (8/20μs)			14	V
CJ	Capacitance	VR = 0V, f = 1MHz			15	pF

PACKAGE MECHANICAL DATA



D!	Inches		Millimeters		
Dim	MIN	MAX	MIN	MAX	
Α	0.0125	0.02	0.32	0.52	
В	0.000	0.002	0.00	0.05	
С	0.037	0.043	0.95	1.080	
D	0.022	0.027	0.55	0.680	
E	0.016	0.024	0.40	0.60	
F	0.008	0.012	0.20	0.30	
Н	0.015Typ.		0.40Тур.		
R	0.001	0.005	0.05	0.15	

Suggested Pad Layout



NOTES:

- 1. CONTROLLING DIMENSIONS ARE IN MILLIMETERS (ANGLES IN DEGREES).
- 2. THIS LAND PATTERN IS FOR REFERENCE PURPOSES ONLY. CONSULT YOUR MANUFACTURING GROUP TO ENSURE YOUR COMPANY'S MANUFACTURING GUIDELINES ARE MET.

REEL SPECIFICATION

P/N	PKG	QTY
ESD9X5V-MS	DFN1006	10000



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